

(0,50mm) .01969"

BTH, BSH SERIES

BASIC BLADE & BEAM HEADER & SOCKET

SPECIFICATIONS

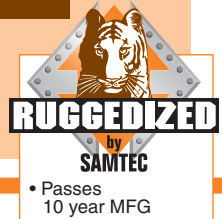
For complete specifications and recommended PCB layouts see www.samtec.com?BTH or www.samtec.com?BSH

- Insulator Material:** LCP
- Contact Material:** Phosphor Bronze
- Plating:** Au or Sn over 50µ" (1,27µm) Ni
- Current Rating:** 1.25A @ 80°C ambient
- Flammability Rating:** UL 94 VO
- Operating Temp Range:** -55°C to +125°C
- Voltage Rating:** 125 VAC
- Max Cycles:** 100
- RoHS Compliant:** Yes



- Processing:** Lead-Free Solderable: Yes
- SMT Lead Coplanarity:** (0,10mm) .004" max (030-090) (0,15mm) .006" max (120-150)
- Board Stacking:** For applications requiring more than two connectors per board or 90 positions or higher, contact ipg@samtec.com

BTH	NO. OF POSITIONS PER ROW	01	PLATING OPTION	D	A	OTHER OPTION
Mates with: BSH		-030, -050, -060, -090, -120, -150			-F = Gold Flash on contact, Matte Tin on tail -L = 10µ" (0,25µm) Gold on contact, Matte Tin on tail -C* = Electro-Polished Selective 50µ" (1,27µm) min Au over 150µ" (3,81µm) Ni on Signal Pins in contact area, 10µ" (0,25µm) min Au over 50µ" (1,27µm) Ni on Ground Plane in contact area, Matte Tin over 50µ" (1,27µm) min Ni on all solder tails	-K = (7,00mm) .276" DIA Polyimide Film Pick & Place Pad -TR = Tape & Reel (120 positions maximum)



MATED HEIGHT

LEAD STYLE	MATED HEIGHT*
-01	(5,00) .197

*Processing conditions will affect mated height.

APPLICATION SPECIFIC

- 30µ" (0,76µm) Gold
- Edge Mount Capability
- 8mm, 11mm, 16 mm, 19mm and 22mm Stack Height (Caution: Some automatic placement/inspection machines may have component height restrictions. Please consult machinery specifications.) (11mm, 16mm, 19mm and 22mm not available with 50 positions)
- Call Samtec.

*Note: -C Plating passes 10 year MFG testing
Note: Some lengths, styles and options are non-standard, non-returnable.

BSH	NO. OF POSITIONS PER ROW	01	PLATING OPTION	D	A	OTHER OPTION
Mates with: BTH		-030, -050, -060, -090, -120, -150			-F = Gold Flash on contact, Matte Tin on tail -L = 10µ" (0,25µm) Gold on contact, Matte Tin on tail -C* = Electro-Polished Selective 50µ" (1,27µm) min Au over 150µ" (3,81µm) Ni on Signal Pins in contact area, 10µ" (0,25µm) min Au over 50µ" (1,27µm) Ni on Ground Plane in contact area, Matte Tin over 50µ" (1,27µm) min Ni on all solder tails	-TR = Tape & Reel (120 positions maximum)

AGILENT LOGIC ANALYZER TEST POINT CONNECTOR
Specify: ASP-65067-01

Due to technical progress, all designs, specifications and components are subject to change without notice.

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